

	Hits	Search Text	DBs
46	0	430/270.1.ccls. and ((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
47	0	430/322.ccls. and ((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
48	0	430/9.ccls. and ((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
49	0	430/311.ccls. and ((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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50	0	((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
51	0	((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

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52	0	((substrate or wafer or under\$4layer or (bottom near4 layer)) same (photoresist or resist or photo\$4cur\$4 or photo\$3imageable) same (novolac or epoxy or resin) same photoactive same (carbonyl near4 acid near8 (generat\$4 or liberat\$4)) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and ((solubilization or solubilizing or soluble or solubility or insoluble) same (prevent\$4 or caus\$4 or inhibit\$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB